

September 28, 2013
Procurement division
Production Headquarters

**For composition list of a product /
analysis report**

1. For composition list of a product

Requirements of composition list

Purchase product					
No.	Sanken Part Number	Name of product	Your Part Number (type name)	Product weight:mg	Your information
1	34*****	DIODE	1S***SY	130	Look at the right

l	Date
n	Your company name
f	Department
o	Person in charge
r	Management positions
m	Title and name of person responsible for response
a	Phone number
t	E-mail address
i	
n	

Component parts (Composition list of a product)						
No.	Component parts name	Manufacturer / Country of Origin	SONY GP Raw materials			
			GB No.	GP raw materials manufacturer ID	Mass of the site:mg	Mass ratio:%
1	Mold Resin	◆●Chemical/Japan	GB No.*****	ID No.****	39	30%
2	Lead Frame	Non-disclosure	-	-	88.775	68%
3	Terminal Plate	○■Metal/Japan	-	-	0.8	1%
4	Si chip	○○Electric/Taiwan	-	-	0.125	0%
5	Die attach	○■Metal/Japan	-	-	1.3	1%
Site total mass(Consistent with your product mass)					130	100%

- *Component parts name ?
- *And mass?
- *Supplier ? (manufacture name, country of origin)
- *SONY recommended products(magnet wire, ink, paint, molding resin, etc.)
- *GP(Designated raw material(recycled resin, and wire)?

No.	Component parts name	Substance Name	CAS No.	Composition:wt%	Substance mass:mg	Purpose of use	Remarks (such as the RoHS exemption applications)
1	Mold Resin	Epoxy resin	-	98	38.22	Seal material	
		Antimony trioxide	1309-64-4	1	0.39	Flame retardant	
		Brominated flame retardants	-	1	0.39	Flame retardant	Not RoHS banned substances
2	Lead Frame	Cu	7440-50-8	99	87.88725	Base	
		Impurities	-	1	0.88775	Impurities	
3	Terminal Plate	Sn	7440-31-5	96.5	0.772	Main component	
		Ag	7440-22-4	3	0.024	Main component	
		Cu	7440-50-8	0.5	0.004	Main component	
4	Si chip	Si	7440-21-3	99.975	0.12498875	Main component	
		As	7440-38-2	0.025	0.0003125	Dopant	
5	Die attach	Sn	7440-31-5	2.5	0.0325	Main component	
		Pb	7439-92-1	95	1.235	Main component	RoHS exemption 7(a)
		Ag	7440-22-4	2.5	0.0325	Main component	
Component total mass(Consistent with your product mass)					130		

- *Substance that constitutes the Component parts? (Substance name, CAS No.)
- * Substance mass?
- *Purpose of use?
- *Do you have to comply with environmental regulations?

- Points to remember
- *Total mass of chemicals, to match the product mass.
 - Order to respond to management and prohibited substances increase in the future.
 - The material non-disclosure, should be described as non-disclosure. However, prohibited or controlled substances, I disclose.
 - * The exemption applications, there are items that are set to disabled time.

2.For analysis report

2-1. Notes Report of result of precision analysis

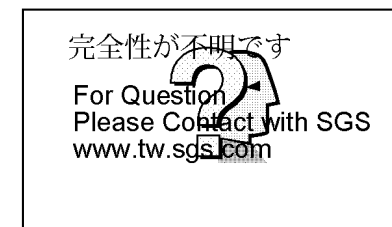
- (1) Refer to IEC62321, pre-treatment for analysis and measurement are executed.
- (2) The process flow for analysis shall be attached.
- (3)The sample's photo for analysis shall be attached.
- (4) The expiration date of the analysis data is one year from the date of the measurement.

Please submit the analysis data within one year from the measurement day.

2-3. <analysis institution>

- (1)The laboratory is authorized certification of ISO/IEC17025, or there are international institutions such as SGS, INTERTEC.
- (2)If you submit SGS TAIWAN's analysis report, please check mark in the upper left Page1.

If this mark is 「 ? 」 we are not able to receive it.



3.For High-Precision Analysis Result List for 6 RoHS Substance

*"High-Precision Analysis Result List for 6 RoHS Substance" is not required if you submit a document that describes the following items.

- a) It is possible to match the "Report of result of precision analysis" and component parts
- b) The name / names of materials / material manufacturer / country of origin / analysis report number of component parts Are listed. (However, the country of origin and the manufacturer acknowledges the "non-disclosure", "Confidential")

Example of description

component parts	material	manufacturer	country of origin	analysis report number
Mold resin	Epoxy resin	◆●chemical	Japan	2013/**/**
Lead frame	Cu	non-disclosure	non-disclosure	JP/2013/**
Terminal Plating	Sn-Cu	○■metal	Japan	D/**/**
Silicon chip	Si	○○electric	Taiwan	KA/2012/**
Die attach	Sn-Pb	○■metal	Japan	JP/2013/**